

Material Specification

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PROJECT

Design name	: TEA1936x Multi Standard 27W Mobile Charging v2		
Board-ID	: TEA1936xDB1475	PCB number	: 0000-000-3998-R2-00
Reference	: Patrick van den Hurk	Date	: 2017-11-16
Size single board	: 48.00 x 41.00 mm.	Size panel board	: 116.00 x 225.00 mm.
Size tolerance	: +0.10 -0.20 mm.	Composition	: 2x5, See Panel Drawing
Total layer(s)	: 2	Board thickness (+/- 10%)	: 0.80 mm.
Basic material	: FR4	Board finish	: ENIG
Cu thickness outer layer, finished	: 70 µm.	Cu thickness inner layer	: -- µm.
SMD technologie	: Yes, both sides	Powerplanes	: No
Used via type(s)	: Through		
Pasta mask	: Yes, both sides	Peel-off mask	: No
Silkscreen	: Yes, both sides	Silkscreen colour	: White
Solder resist	: Yes, both sides	Solder resist colour	: Green

PLOTTER INFORMATION

Units	: Millimeters
Gerber type	: RS274X
Data type	: Absolute X/Y-positive
Output code	: ASCII
Resolution	: 1/10000 mm.

NC DRILL PARAMETERS

Units	: Imperial
Machine	: Excellon
Data format	: 3.5
Output code	: ASCII
Resolution	: 1/10000 inch

NON PLATED THROUGH HOLES

Hole size tolerance, ≤ 0.2 mm.	: +0.05 -0.05 mm.
≥ 0.3 mm.	: +0.1 -0.1mm.
Position tolerance	: +0.1 -0.1mm.

PLATED THROUGH HOLES

Hole size tolerance, ≤ 0.2 mm.	: +0.05 -0.05 mm.
≥ 0.3 mm.	: +0.1 -0.1mm.
Position tolerance	: +0.1 -0.1mm.

MILL BOARD OUTLINES

The position from the boardoutline and boardcutouts represent the exact centerline to complete the dimensions. The milltool has to be positioned near the centerline with a offset half the diameter from the tool.

SCORE BOARD OUTLINES

The position from the boardoutline represent the exact centerline to complete the dimensions. The score tool has to be positioned at the centerline.

BOARD PROPERTIES

Min. isolation outer layer	: 190 µm.	Min. isolation inner layer	: --- µm.
Min. track width outer layer	: 200 µm.	Min. track width inner layer	: --- µm.
Min. hole diameter	: 0.2 mm.		

REMARKS

Manufacturer code allowed.

NXP Logo has to be filled.

Milling Through copper allowed.

Single board has to be panelized, the number of times see panel drawing.

Panel has breakaway edges (10.00mm).

Panel has scoring grooves, both directions.

Add text: 9999-000-39982 and has to be done only in the breakaway edge.

Create a top and bottom paste file from the panel. Send this back to customer.

Single boards on the left side column of the panel has to be rotated 180 degrees.

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FILES INCLUDED

Top Paste Mask	: 0000-000-3998-R2-00_SPT.gbx
Top Silkscreen	: 0000-000-3998-R2-00_SST.gbx
Top Solder Resist	: 0000-000-3998-R2-00_SMT.gbx
Top Signal Layer (L1)	: 0000-000-3998-R2-00_TOP.gbx
Bottom Signal Layer (L2)	: 0000-000-3998-R2-00_BOT.gbx
Bottom Solder Resist	: 0000-000-3998-R2-00_SMB.gbx
Bottom Silkscreen	: 0000-000-3998-R2-00_SSB.gbx
Bottom Paste Mask	: 0000-000-3998-R2-00_SPB.gbx
Milling Non Plated	: 0000-000-3998-R2-00_MNP.gbx
Milling Plated	: 0000-000-3998-R2-00_MPL.gbx
NC Drill	: 0000-000-3998-R2-00-1-2.drl
NC Route (slotted holes)	: 0000-000-3998-R2-00.rou
Mechanical Dimensions	: 0000-000-3998-R2-00_DRD.gbx/.pdf
PCB Information (reference stack)	: 0000-000-3998-R2-00_PCB.gbx/.pdf
Panel Drawing	: 0000-000-3998-R2-00_PNL.gbx/.pdf
This File	: 0000-000-3998-R2-00_MSP.pdf